

Title (en)  
HEAT RADIATION FAN

Title (de)  
HITZESTRAHLUNGSLÜFTER

Title (fr)  
VENTILATEUR À RAYONNEMENT THERMIQUE

Publication  
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Application  
**EP 10838529 A 20100223**

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Abstract (en)  
[origin: EP2518327A1] A cooling fan, which may be installed on a corresponding position of the cooling fins of a CPU or a cooling hole-plate of a computer mainframe, includes: a fan body (3), a fan frame (2) and a fan impeller (1). The fan frame (2) is circular in shape. The fan body (3) is arranged along the outer circumference of the fan frame (2). The fan impeller (1) is installed in the fan frame (2). A rubber layer (4), which is formed by secondary injection molding, is arranged at the outer surface of the fan body (3) and the contact parts between the cooling fins and the upper and lower edges of the fan frame (2), respectively. Through holes (31) are provided at the upper and lower parts of four end corners of the fan body (3), respectively, and rubber layers are also provided at the inner walls of the through holes, so that after secondary injection molding, the upper edges of the through holes are made level with the corresponding upper and lower edges of the fan frame (2). The present invention can achieve flexible touch between the cooling fan and the cooling fins or the cooling hole-plate of a computer mainframe, thereby effectively offsetting longitudinal and transverse impact and vibration and reducing noise.

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